

**Type 1040TD/Slow Blow Brick Chipfuse**

1040TD系列/慢断方型保险丝



**Description**

- ➔ Slow blow surface-mount fuse  
慢断表面贴装保险丝
- ➔ Designed according to IEC60127-4  
根据IEC60127-4设计
- ➔ Solder immersion compatible  
浸焊兼容

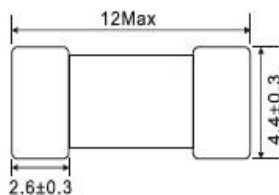
**Features 产品特征**

- ➔ 250VAC voltage rating  
250VAC电压等级
- ➔ Slow blow  
慢断
- ➔ RoHS compliant  
符合RoHS要求

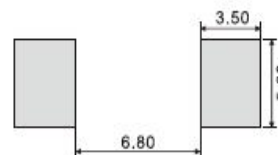
**Applications 产品应用**

- ➔ Lighting ballast  
照明镇流器
- ➔ Transformerless AC/DC converte circuit  
变压器交流/直流转换电路
- ➔ AC/DC adaptor primary protection  
AC/DC适配器主保护
- ➔ High dc voltage power distribution syste  
高直流电压配电系统

**Dimensions(Unit:mm)尺寸 (单位: mm)**



**Recommended Pad Layout(mm)**



**Electrical Characteristics 熔断特性**

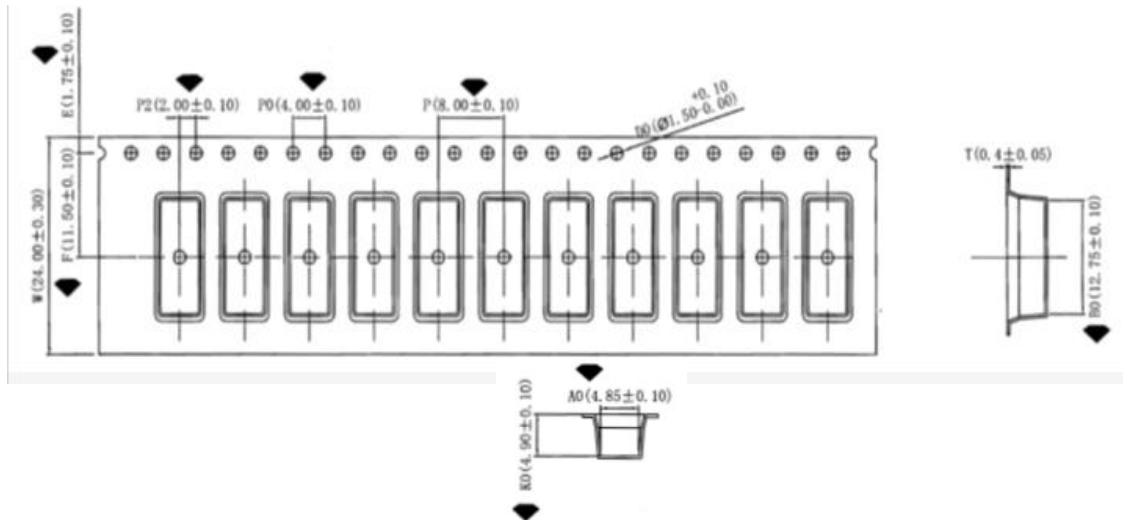
Electrical Characteristics 熔断特性		
Ampere Rating	% of Amp Rating	Opening Time
500mA-5A	125%	1Hours Minimum
	200%	120 Seconds Maximum
	1000%	10ms Minimum

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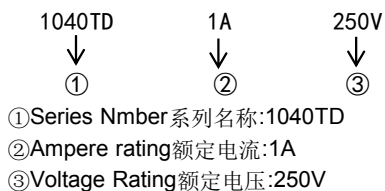
**Electrical Specifications 电气特性**

Catalog Number	Ampere Rated In	Marking	Voltage Rating(V) Interrupting Rating (A)	Normal Resistance Cold(Ohm)	Normal Melting $I^2T(A^2sec)$
1040TD500mA	500mA	T0.5	150A@125V/250VAC 150A@125VDC 800A@80V/72V/ 63V/32VDC	0.2270	0.43
1040TD630mA	630mA	T0.63		0.1570	0.80
1040TD800mA	800mA	T0.8		0.1300	1.40
1040TD1A	1A	T1.5		0.0867	2.70
1040TD1.25A	1.25A	T1.25		0.0602	5.20
1040TD1.6A	1.6A	T1.6		0.0443	9.70
1040TD2A	2A	T2		0.0335	5.44
1040TD2.5A	2.5A	T2.5		0.0278	8.00
1040TD3.15A	3.15A	T3.15		0.0204	14.00
1040TD4A	4A	T4		0.0158	21.00
1040TD5A	5A	T5		0.0124	40.00

**Packaging and Type Designation 包装和型号名称**



**Formation of Type Designation 类型命名的形成**

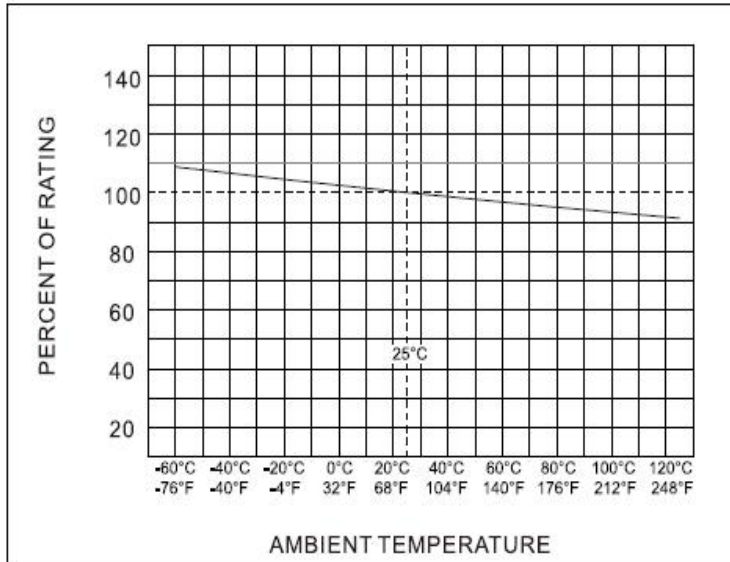


**Packaging 包装**

On Tape: 1040TD-1000pcs Per Reel, 6000pcs Outer Box

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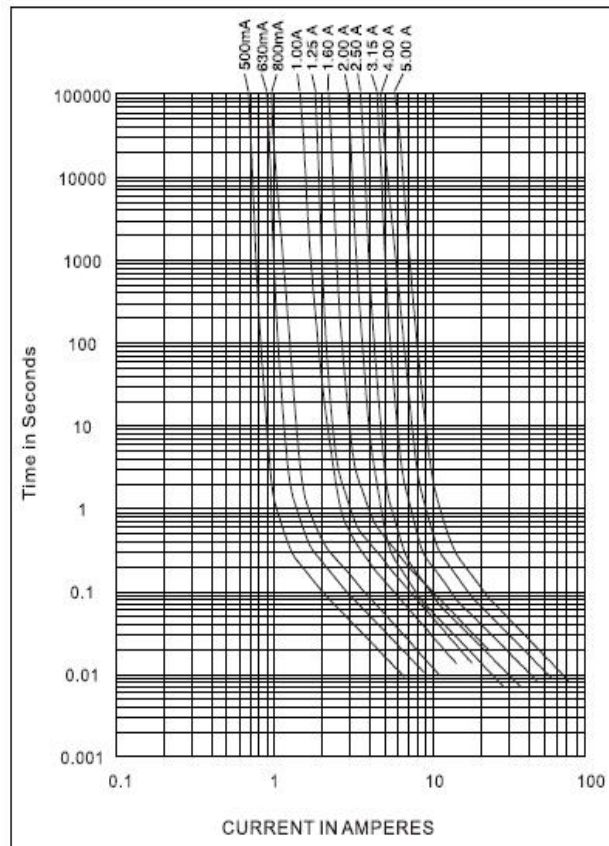
Temperature Rerating Curve 额定温度曲线



**Note:**

Derating depicted in this curve is in addition to the standard derating of 25% for continuous operation.

Time-Current Characteristics 熔断时间特性表



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**Soldering Parameters 焊接参数**

Reflow Condition 回流条件		Pb-Free assembly 无铅制程
Heat Pre	Temperature Min ( $T_s$ )	150°C
	Temperature Max ( $T_s$ )	200°C
	Time (Min to Max) ( $t_s$ )	60-120secs
Average ramp up rate (Liquidus) Temp ( $T_L$ ) to peak		3°C/second max
$T_s$ (max) to $T_L$ - Ramp-up Rate		3°C/second max
Reflow	-Temperature ( $T_L$ ) (Liquidus)	217°C
	Time (Min to Max) ( $t_L$ )	60-90 seconds
Peak Temperature ( $T_p$ )		260 <sup>-0/-5</sup> °C
Time within 5°C of actual peak Temperature ( $t_p$ )		20-40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature ( $T_p$ )		8 minutes max.
Do not exceed		260°C

